

FASTON TAB FOR BSH

1. INTRODUCTION

1.1 Purpose

The purpose of this test is to evaluate the performance of FASTON TAB FOR BSH. Testing was performed on below products to determine its compliance with the requirements of 108-106562 Rev.A.

1.2 Scope

This specification covers the environment and mechanical performance for FASTON TAB FOR BSH. Testing was performed at TE Connectivity Shanghai Electrical Test Laboratory (Building ID 554) between 2021-04-19 and 2021-04-30. The associated test number is TP-21-00909.

1.3 Conclusion

Based on the test results, Solderability Test: Meet spec.
 Mating Force & Un-mating Force: Judged by client.
 The results in this report only effect on the sampling specimens.

1.4 Test Specimens

Specimens with the following part numbers were used for test:

Test Group	Part No.	Description	Qty. (pcs)	Part No.	Description	Qty. (pcs)	Comments
1	2376579-2	250 FASTON PCB TAB TPBR	5	/	/	/	/
	2376582-2	250 FASTON PCB TAB TPBR	5	/	/	/	/
	2376591-2	250 FASTON PCB TAB TPBR	5	/	/	/	/
	2376595-2	250 FASTON PCB TAB TPBR	5	/	/	/	/
2	2376582-2	250 FASTON PCB TAB TPBR	6	RSB 8260.158	STOCKO RECEPTACLE	6	/
	RMB6306 P1.3-6.3	STOCKO TAB	6	RSB 8260.158	STOCKO RECEPTACLE	6	/

1.5 Test Sequence

Test Item	Test Group	
	1	2
	Test Sequence	
Solderability Test	1	
Mating Force & Un-mating Force without latch		1

Note: a). Test group defined per customer requirement.
 b). Numbers indicate sequence in which tests are performed.

1.6 Environmental Conditions

Unless otherwise stated, the following environmental conditions prevailed during testing:

Temperature: 15°C to 35°C
 Relative Humidity: 25% to 75%

2. TEST PROCEDUES

2.1 Mating Force & Un-mating Force without latch

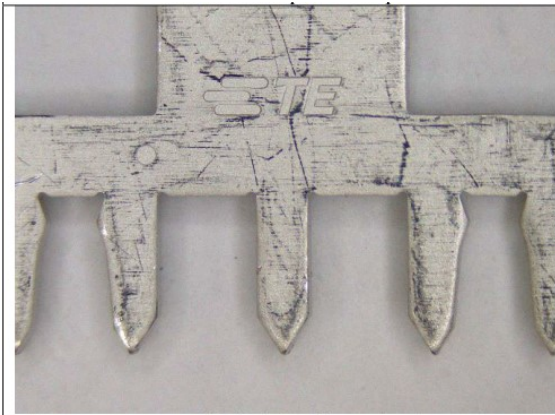
Measure force necessary to mate/un-mate samples at maximum rate of 25.4 mm a minute.
 Test Method: Customized Requirement
 Requirement: N/A

2.2 Solderability Test

Preconditioning: All specimens shall be subjected to 155 °C steam aging for 16 hours.
 Subject specimens to the condition of lead-free solder (Sn-Ag-Cu), Solder Temperature:(267-270) °C;
 Immersion duration: (1.5-5) s.
 Test Method: Customized Requirement
 Requirement: More than 95% coverage

3. SUMMARY OF TEST

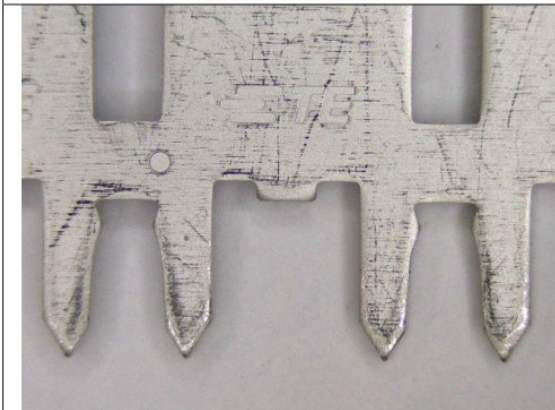
Group	SN	Description	Test Item	Qty(pcs)	Test Result				Requirement	Conclusion
					Max	Min	Avg	Unit		
1	1	2376579-2	Solderability Test	5	More than 95% coverage			/	More than 95% coverage.	Meet Spec
	1	2376582-2	Solderability Test	5	More than 95% coverage			/		Meet Spec
	1	2376591-2	Solderability Test	5	More than 95% coverage			/		Meet Spec
	1	2376595-2	Solderability Test	5	More than 95% coverage			/		Meet Spec



2376579-2 Before test



2376579-2 After test



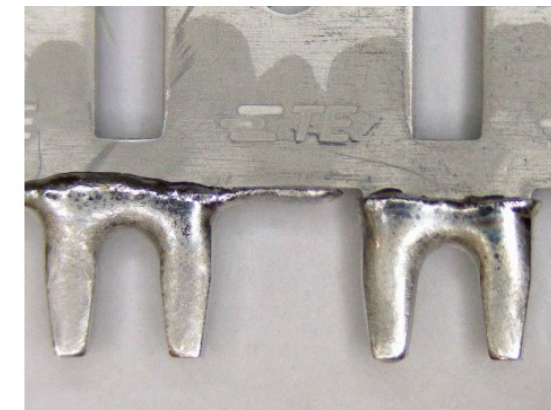
2376582-2 Before test



2376582-2 After test



2376591-2 Before test



2376591-2 After test



2376595-2 Before test



2376595-2 After test

Group	SN	Description	Test Item	Qty(pcs)	Test Result		Requirement
					Avg	Unit	
2	1	RMB6306 P1.3-6.3	Mating Force	6	16.5	N	/
	1	2376582-2	Mating Force	6	18.8	N	/
	1	RMB6306 P1.3-6.3	Un-mating Force	6	18.2	N	/
	1	2376582-2	Un-mating Force	6	18.4	N	/

NOTE: Due to the four parts using the same raw material and plating, 2376582-2 will be representative in the mating force test.

----- **END OF REPORT** -----